

Conferences

1. **Oct. 2016, IEEE 22nd International Symposium for Design and Technology in Electronic Packaging, (SIITME 2016), “Adaptive user interface for higher education based on web technology”**, oral session, Oradea, Romania.
2. **March 2017, 4. Tag der Forschung Technische Hochschule Deggendorf, “Education 4.0: Effiziente virtuelle Weiterbildung“**, poster, Germany.
3. **June 2017, INDIGO Conference – East-Bavarian Internet and Digitalization Network, “Education 4.0: Methoden zur Qualifizierung von Arbeitnehmer“**, poster, OTH Amberg-Weiden, Germany.
4. **Sept. 2017, 16. E-Learning Tag, “Education 4.0 revolutioniert E-Learning”**, poster and oral session, FH Joanneum, Graz, Austria.
5. **Oct. 2017, IEEE 23rd International Symposium for Design and Technology in Electronic Packaging, (SIITME 2017) “Education 4.0 for Tall Thin Engineer in a data driven society”**, and **“Education 4.0: Fostering Students performance with Machine Learning Methods”**, oral session, Constanta, Romania.
6. **March 2018, 5th Tag der Forschung Technische Hochschule Deggendorf, “Education 4.0 for Tall Thin Engineer in a data driven society”**, poster, Germany.
7. **Sept. 2018, 17th E-Learning Tagung Jetzt für die Zukunft - Ideen, Konzepte und Projekte - FH Joanneum, “Smarter Blended Learning 4.0 Prozess”**, oral session, http://oer.fh-joanneum.at/zml/wp-content/uploads/2018/09/ELT-Tagungsband2018_final.pdf, Graz, Austria.
8. **Oct. 2018, IEEE 24th International Symposium for Design and Technology in Electronic Packaging, “Education 4.0 - Artificial Intelligence assisted higher Education: Early recognition System with Machine Learning to support Students Success”**, oral session, Iasi, Romania.
9. **April 2019, 6th Tag der Forschung Technische Hochschule Deggendorf, “Education 4.0 Artificial Intelligence assisted higher education”**, poster and oral session, Germany
10. **Oct. 2019, IEEE 25th International Symposium for Design and Technology in Electronic Packaging (SIITME 2019), “Education 4.0 - Jump to Innovation IoT in Higher Education”**, and **“Enabling IoT in Education 4.0 with Biosensors from Wearables and Artificial Intelligence”**, Cluj-Napoca, Romania
11. **Sept. 2020, 19th E-learning Tagung Innovation & Reflexion, FH Joanneum, “Education 4.0: IoT- und CoP-unterstützte Smarte E-Learning Prozesse”**, cyber event, https://oer.fh-joanneum.at/zml/wp-content/uploads/2020/09/ELT-Tagungsband2020_5.1_onlineversion.pdf, Graz, Austria.
12. **Oct. 2020, IEEE 26th International Symposium for Design and Technology in Electronic Packaging (SIITME 2020), “Education 4.0: An Adaptive Framework with Artificial Intelligence, Raspberry Pi and Wearables- Innovation for Creating Value”**, oral session, fully virtual, Pitesti, Romania.
13. **Nov. 2020, IEEE 14th International Symposium on Electronics and Telecommunications (ISETC2020), “Education 4.0: Smart Blended Learning assisted by Artificial Intelligence, Biofeedback, and Sensors”**, oral session, fully virtual, Timisoara, Romania.
14. **April 2021, IEEE 12th Global Engineering Education Conference (EDUCON 2021), “Women in Engineering”, “Education 4.0: AI empowers Smart Blended Learning Process with Biofeedback”**, fully virtual, Vienna, Austria.
15. **Oct. 2021, IEEE 27th International Symposium for Design and Technology in Electronic Packaging, SIITME 2021, “Education 4.0: Innovation Learning Lab for AI: Analysis and Concept Proposal”**, oral presentation, fully virtual, Romania.
Posters assessor committee and social media committee chair.
16. **Nov 2021, 4th ISM 2021 International Conference on Industry 4.0 and Smart Manufacturing**, fully virtual, Linz, Austria, member of the international program committee, **Session chair Engineering Education 4.0**, <https://www.msc-les.org/ism2021/>.
17. **May 2022, Forum der Lehre, Bayziel Didaktikzentrum, „KI- und IoT- unterstützter Blended Learning Prozess Education 4.0 – Werkstatttrunde“**, Monica Ciolacu, Universität Passau. <https://www.didaktikzentrum.de/programm/aktuelles-programm/details/4-diz-termin?xref=162380:forum-der-lehre-2022>
18. **Sept 2022, IEEE 9th ESTC Electronics System-Integration Technology Conference**, Sibiu, Romania <https://www.estc-conference.net/home>.
Session Chair Biomedical Application Packaging.
“Virtual Collaboration with Agile Methods in Engineering Education 4.0 – Jump in the New Normal with Digital Innovation Units” oral presentation.

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19. **Nov. 2022, 5th International Conference on Industry 4.0 and Smart Manufacturing (ISM 2022)**, Upper Austria University of Applied Sciences - Hagenberg Campus - Linz, Austria, <https://www.msc-les.org/ism2022/>.
Member of the international program committee.
Session chair Education and training challenges for Industry 4.0 professionals
Round table "The Industrial Engineering Education 4.0" Chair Monica Ciolacu – University of Passau, Germany, The Industrial Engineering 4.0 Education Initiative (IEEI 4.0) has been introduced. The IEEI4.0 is supported by a working group within the ISM that aims to analyze Industry 4.0 education at the international level. Representatives from Italy, Austria, Germany, and Romania provided interesting data. A roundtable was set up to share experiences and ideas about how didactics and teaching are changing for industrial engineering. Paper **"Fostering Engineering Education 4.0 paradigm -Facing the Pandemic and VUCA World"**.
20. **March 2023 - 20th REV International Conference on Remote Engineering and Virtual Instrumentation (REV 2023)** International Association of Online Engineering (IAOE) Aristotle University of Thessaloniki, Greece. 01-03 March 2023.
Special Session Chair: "Fostering Engineering Education from 4.0 to 5.0 - Towards a more sustainable, resilient, and human-centric industry (EngEdu 5.0)", Chair: Monica Ciolacu https://www.rev-conference.org/current/cfp_EngEdu.php
Workshop "University 4.0: Imagined Cyborg or Inevitable Reality?", University of Passau, Germany; Princess Sumaya University for Technology, Jordan, Hashemite Kingdom of; National Technological University, Argentina; Polytechnic of Porto, Portugal, TU Dortmund University, Germany, University of Southern Queensland, Australia
https://www.conftool.com/rev-conference/index.php?page=browseSessions&form_session=358&presentations
21. **June 2023, expat'23** – 6th IEEE International Conference on Remote Engineering and Virtual Instrumentation University of Evora, Portugal. <https://expat.org.pt/expat23/programme/>
Jury Committee Online Experimentation Demos Session
Paper **"Building a Sustainable, Student-centred and Resilient Higher Education 5.0 through Intra- and Interinstitutional Collaborations"** by Monica Ciolacu, Florian Stelzer, Matthias Brandl, Kathrin Plank, Werner Gamerith, Christina Hansen, Tamara Rachbauer and Michaela Würdinger-Gaidas University of Passau, Germany.
Special Session Chair: "Online Experimentation", Chairs: Monica Ciolacu and Unai Hernandez-Jayo.